ABSTRACT

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH LEAD ENCAPSULATION AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit packaging system includes: forming a package paddle; forming a lead adjacent the package paddle, the lead having a hole in a lead body top side and a lead ridge protruding from a lead non-horizontal side; mounting an integrated circuit over the package paddle; connecting an electrical connector to the lead and the integrated circuit; and forming a fill layer within the hole.
(Fig 1)